



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of: **TANIGUCHI, et al.**

Serial No.: **09/836,182**

Filed: **April 18, 2001**

Group Art Unit: **2827**

Examiner: **MITCHELL, James M.**

P.T.O. Confirmation No.: **7961**

For: **METHOD OF FABRICATING SEMICONDUCTOR
HAVING THROUGH HOLE**

BOX AF

Commissioner for Patents
Washington, D.C. 20231

November 22, 2002

Sir:

In response to the Office Action dated **August 13, 2002**, extended by one month by an extension of time filed herewith, please amend the above-identified application as follows:

IN THE CLAIMS:

Please amend Claim 14, as follows:

14. (Four Times Amended) A semiconductor device comprising a semiconductor chip, a tape for mounting said semiconductor chip thereto, an adhesive resin layer interposed between said semiconductor chip and said tape, and solder balls arranged on said tape, characterized in that said tape has no artificially produced vapor escape holes formed therein, and is of a material having high water permeability of $10 \text{ g/m}^2 \cdot 24\text{H}$ or more, sufficient to prevent cracking and bulging of said

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U.S. Patent Application Serial No. 09/836,182

semiconductor device which might occur when the solder balls are reflowed after said semiconductor device absorbs moisture.